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Micron rolls out 232-layer NAND, raising storage ambitions

Micron Technology said it started volume production of the world's first 232-layer NAND storage solution, a move which comes almost exactly a year after the company touted 176-layer NAND, and could enable a new generation of storage devices faster and more robust than anything currently on the market.

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TALK TO US

Infineon's new HYPERRAM™ memory chip doubles bandwidth for low pin-count

Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) has added HYPERRAM™ 3.0 to its portfolio of high-bandwidth, low-pin count memory solutions. The device features a new,16-bit extended version of the HyperBus™ interface that doubles throughput to 800 MBps. With HYPERRAM 3.0, Infineon offers a portfolio of high-bandwidth memories with low pin-count and low-power.

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eMMC Holds Its Own Against UFS

The embedded MultiMediaCard (eMMC) standard is no longer being updated. But that's not keeping some vendors from innovating around the NAND flash storage device for use cases where it's still the best option.

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Future Horizons Ltd, • 44 Bethel Road • Sevenoaks • Kent TN13 3UE • England
Tel: +44 1732 740440 • Fax: +44 1732 740442
e-mail: mail@futurehorizons.com• http://www.futurehorizons.com/
Affiliates in Europe, India, Israel, Japan, Russian, San Jose California, USA

Intel's bad Q2 drowns out its CHIPS Act celebration

Intel announced second quarter 2022 earnings on the same day that Congress passed the CHIPS Act, of which Intel is seen to be a huge beneficiary, so it should have been a great day at Intel, but woeful quarterly numbers ruined the celebration.

After delivering the downbeat earnings news, which included revenue for the quarter 15% below original guidance, Intel CEO Pat Gelsigner tried to point to the approval of the CHIPS Act as good news for Intel's future. But, Intel CFO David Zinsner acknowledged that the company is not likely to see any of that government money until sometime next year, and analysts seemed unmoved by Intel's promises of a brighter future.

Micron rolls out 232-layer NAND, raising storage ambitions

Micron Technology said it started volume production of the world's first 232-layer NAND storage solution, a move which comes almost exactly a year after the company touted 176-layer NAND, and could enable a new generation of storage devices faster and more robust than anything currently on the market.

"Micron's 232-layer NAND is a watershed moment for storage innovation as first proof of the capability to scale 3D NAND to more than 200 layers in production," said Scott DeBoer, executive vice president of technology and products at Micron. "This groundbreaking technology required extensive innovation, including advanced process capabilities to create high aspect ratio structures, novel materials advancements and leading-edge design enhancements that build on our market-leading 176-layer NAND technology."

Nvidia unleashes AI Enterprise 2.1 software suite

Nvidia this week announced AI Enterprise 2.1, the latest version of its enterprise software cloud environment, a move that comes about seven months after the company rolled out Version 1.1.'

That earlier version aimed to broaden availability and appeal of the platform by extending it to support containerized AI via VMware's Vsphere on Tanzu. Now, Version 2.1 is targeted at reaching even more AI workloads where they live on hybrid or multi-cloud environments.

AI Enterprise 2.1 accomplishes this through support for Red Hat OpenShift running in the public cloud and the new Microsoft Azure NVads A10 v5 series. These are the first Nvidia virtual GPU instances offered from the public cloud, which enables affordable GPU sharing, Nvidia stated in a blog post.

Infineon's new HYPERRAM™ memory chip doubles bandwidth for low pin-count, high-performance solutions

Munich, Germany – 2 August, 2022 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) has added HYPERRAM™ 3.0 to its portfolio of high-bandwidth, low-pin count memory solutions. The device features a new,16-bit extended version of the HyperBus™ interface that doubles throughput to 800 MBps. With HYPERRAM 3.0, Infineon offers a portfolio of high-bandwidth memories with low pin-count and low-power. It is a perfect fit for applications requiring expansion RAM memory, including video buffering, factory automation, Artificial Intelligence of Things (AIoT) and automotive vehicle-to-everything (V2X), as well as applications requiring scratch-pad memory for intense mathematical calculations.

"With nearly three decades of memory solutions knowledge, we are excited to bring another industry-first to the market. The new HYPERRAM 3.0 memory solutions achieve a far higher throughput-per-pin than existing technologies in the market such as PSRAMs and SDR DRAMs," said Ramesh Chettuvetty, Senior Director of Applications and Marketing at Infineon's Automotive Division. "Our low-power features enable better power consumption, without sacrificing throughput, which also makes this memory ideal for industrial and IoT solutions.

eMMC Holds Its Own Against UFS

The embedded MultiMediaCard (eMMC) standard is no longer being updated. But that's not keeping some vendors from innovating around the NAND flash storage device for use cases where it's still the best option.

While Universal Flash Storage (UFS) was trumpeted as widely replacing eMMC when it debuted, it's overkill for some applications. In an interview with EE Times, Eric Spanneut, vice president of flash global product management for Western Digital's flash business unit, said eMMC works best for mid–range mobile devices and thin–and–light entry–level compute devices, as well as wide range of emerging applications. "eMMC is here to stay for a very long time," he said.

With little fanfare, the company recently introduced its iNAND EM141 Embedded Flash Device, designed for applications that require high performance, reliable data storage, a small form factor, and efficient power consumption.